

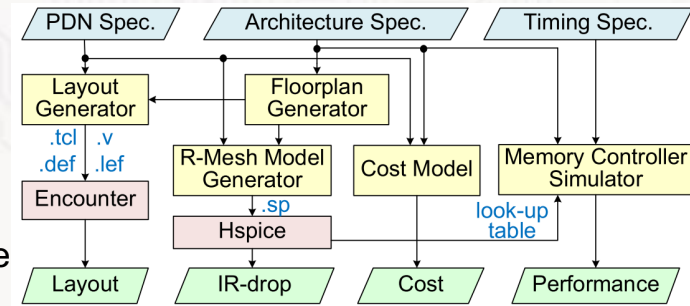
- Design Automation
- 2.5D/3D IC Design & Packaging
- VLSI Digital Design
- Power & Signal Integrity
- Thermal & Reliability

<https://you.uark.edu/ypeng>



## Energy-Efficient-Electronic Design Automation (E<sup>3</sup>DA)

- Algorithms
- Methodology
- CAD Platform
- CAD Flow
- HW/SW Co-design
- Multi-Objective Optimization

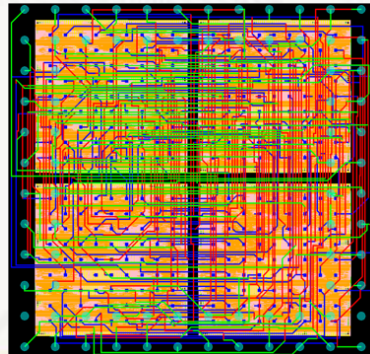


Computer-Aided Design

## 2.5D/3D IC Design and Optimization

### Advanced Packaging and Stacked Dies

- 2.5D Fan-Out Wafer-Level-Packaging
- Face-to-back and Face-to-face bonded 3D IC Design
- Physical Design
- Analysis & Optimization
- Heterogeneous Integration



## Power and Signal Integrity

### Design for Reliability

- RLGC Parasitic Extraction
- Modeling and Simulation
- Timing/Power/Noise Analysis
- Die-to-Package Co-Analysis
- Electro-Thermal Co-Design
- Processor-Memory Co-Optimization

